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wherein the second portion has a shape so as to be superposed on and inside
the first portion except the end part.

Sub C4
B³
13. (Amended) A semiconductor device comprising:
at least one semiconductor chip; and
a substrate which has a first portion and a second portion to be superposed on
the first portion, and on which the semiconductor chip is mounted,
wherein the first portion includes an end part as a positioning reference; and
wherein the second portion has a shape so as to be superposed inside the first
portion and avoid being superposed over the end part of the first portion.

Sub D1
B⁴
15. (Amended) The semiconductor device as defined in claim 13,
wherein the interconnect substrate as defined in claim 1 is used as the
substrate.

16. (Twice Amended) A circuit board on which is mounted the semiconductor
device as defined in claim 13.

REMARKS

Claims 1-20 are pending herein. By this Amendment, the specification is amended to recite the history of the application. Claims 1 and 13 are amended to recite that the second portion has a shape so as to be superposed on and inside the first portion. Support for the amendment is found in the specification at, for example, page 27, lines 2-5. Claim 15 is amended to remove multiple dependency. Claim 16 is amended to fully comply with the requirements of 35 U.S.C. §112, second paragraph. No new matter is added.

The attached Appendix includes a marked-up copy of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).